



BGA, CSP & MLF/LLP REWORK & REPAIR MINI-SEMINAR

Date: Thursday, May 8th.

Location: STI Training Room
102 Tribble Drive
Madison, AL 35758

Time: 8:00 a.m. to 12:00

Lunch served at 12:00

Fee: \$20.00 per attendee



Seminar Timing

- ◆ 30 min multi-media presentation
- ◆ 2.5 hour hands-on demonstrations & instructions
- ◆ Question & Answer session

Applications/Topics

- ◆ Repair
- ◆ Rework
- ◆ Low Volume Assembly
- ◆ Prototyping
- ◆ Placement
- ◆ Screen Printing for Single Components
- ◆ Flux Gel Deposition for BGA/CSP Rework & Repair
- ◆ Temperature Profiling for Rework and Repair
- ◆ Rework & Repair Site Preparation

Who Should Attend

- ◆ Manufacturing Engineers
- ◆ Production Managers
- ◆ Production Supervisors
- ◆ SMT Process Engineers
- ◆ Quality Assurance Managers
- ◆ Production Engineers
- ◆ Repair Managers & Technicians
- ◆ R & D Managers

**Limited Spots
Available
Act Now!!!**



◆ R.S.V.P Form

E-mail completed form or call:

Ann Duncan

PH: 256-705-5512/Fax: 256-461-9566

aduncan@stielectronicsinc.com

First Name

Last Name

Company

Phone

Email Address _____

Yes! I will attend the seminar!

Number of people attending: _____

No, I cannot attend.

Please send information to me at:

Street Address _____

City

State

Zip

***Remit payment to STI Electronics Inc.**

